

# Designing DC-Blocking Capacitor Transitions to Enable 56Gbps NRZ & 112Gbps PAM4

Scotty Neally, Samtec Teraspeed Consulting  
Scott McMorrow, Samtec Teraspeed Consulting



# Speakers



## Scotty Neally

*Signal Integrity Consultant*  
Samtec Teraspeed Consulting

Scotty Neally is an experienced signal integrity consultant with a background in high density PCB design and measurement, automation of signal integrity design flows, and currently focuses on system design for emerging technologies.



## Scott McMorrow

*CTO, Signal Integrity Products*  
Samtec Teraspeed Consulting

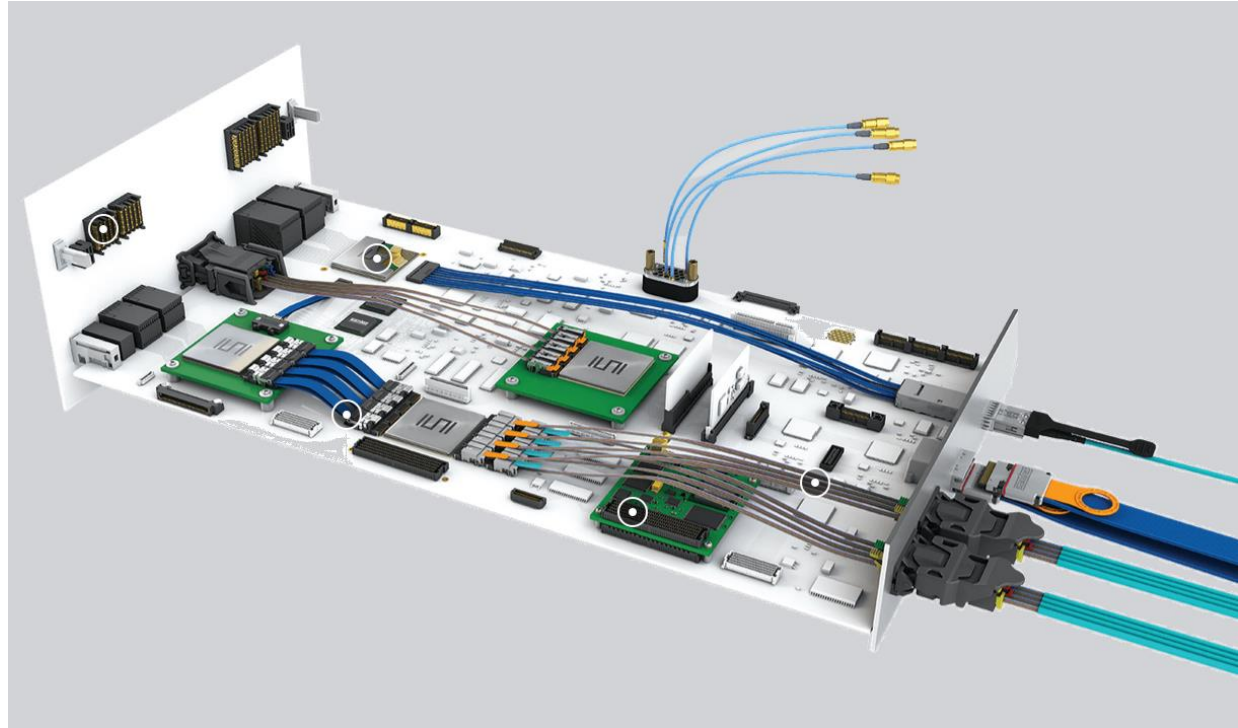
Scott McMorrow is an expert in high-performance design and signal integrity engineering, with a broad background in complex system design, interconnect and signal integrity engineering, modeling and measurement methodology, and professional training, spanning over 25 years.



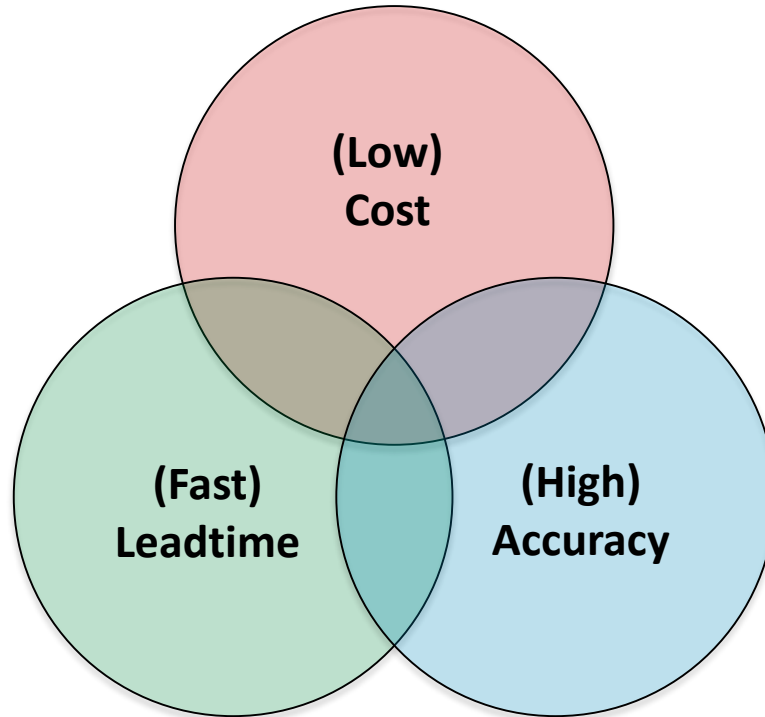
# System Design

- Tradeoffs

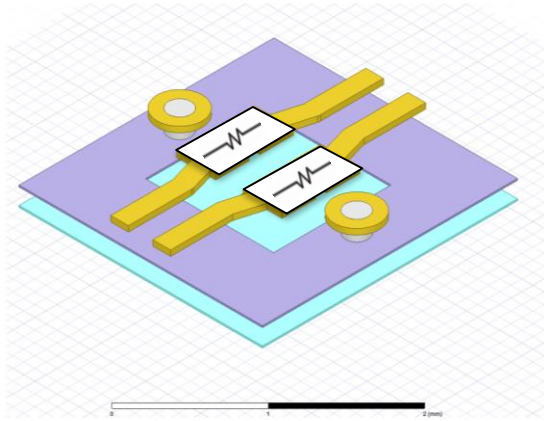
- Cost
- Leadtime
- Performance
  - *Reliability*



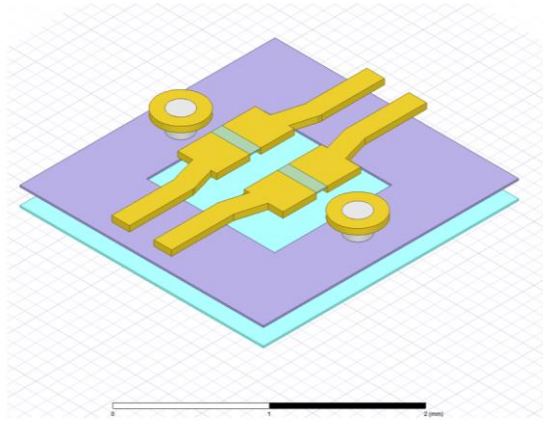
# Decision Diagram



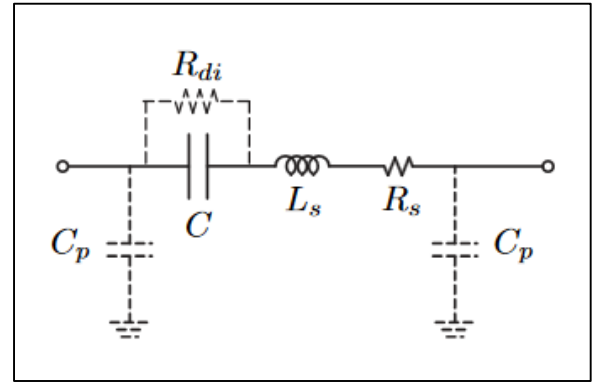
# Traditional Capacitor Models



Shunting Resistor



PEC Plane

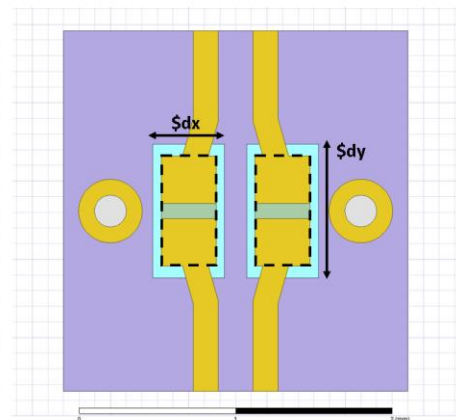
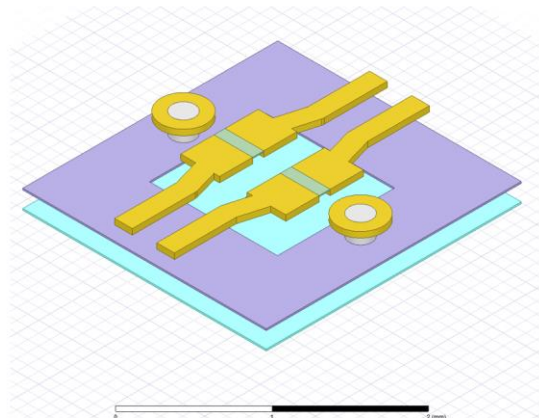


RLC Model

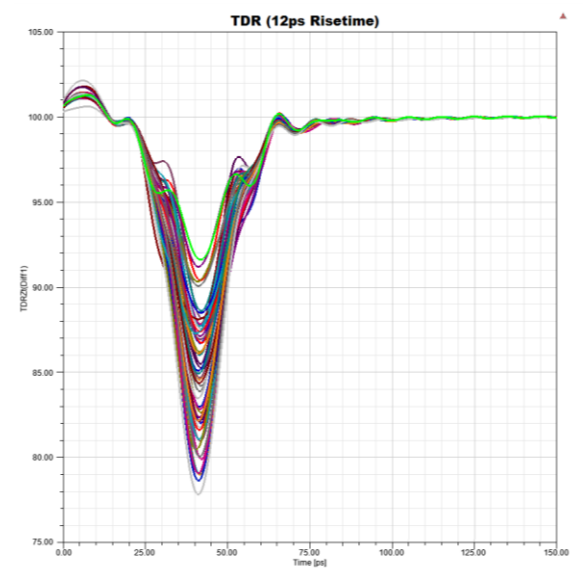
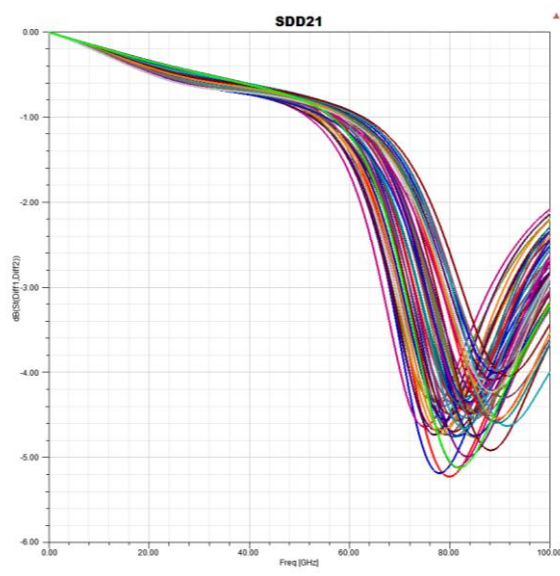
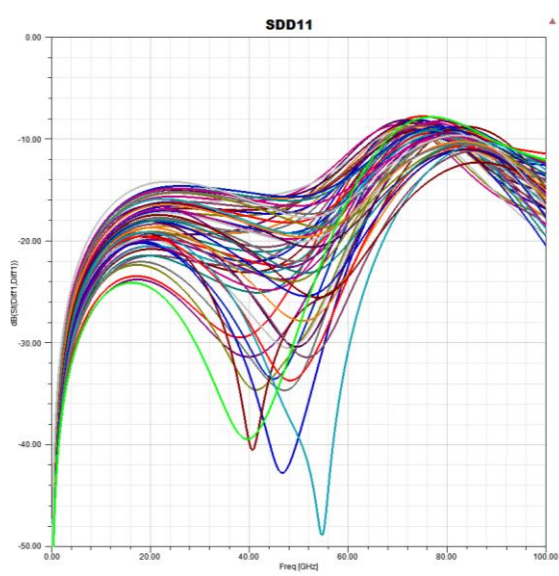


# DC Blocking Capacitor Design Layout

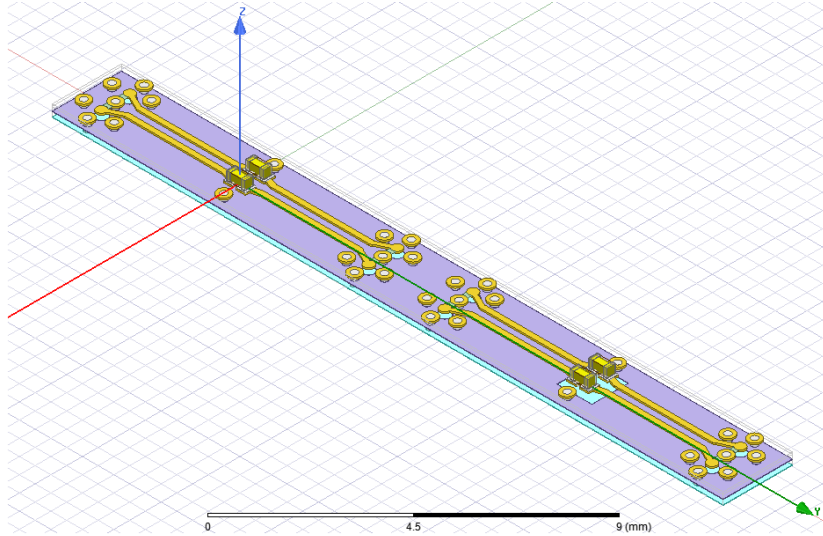
Lyr	Image	Vendor
✓CM	1.400 mils	
✓L1	2.400 mils MIX Base Cu: 0.50 oz 1.000 mils VLP-2	Isola
✓L2	5.000 mils Dk: 3.17 I-TERA MT40 (2-1067)	Isola
	0.600 mils MIX Base Cu: 0.50 oz VLP-2	Isola
	5.430 mils Dk: 3.08 I-TERA MT40 1067 (76.0%)	Isola
	Dk: 3.08 I-TERA MT40 1067 (76.0%)	Isola
✓L3	0.600 mils P/G Base Cu: 0.50 oz RTF	Isola
✓L4	30.000 mils Dk: 3.38 I-TERA MT40 (3.38 Dk)	Isola
	0.600 mils P/G Base Cu: 0.50 oz RTF	Isola
	5.418 mils Dk: 3.08 I-TERA MT40 1067 (76.0%)	Isola
	Dk: 3.08 I-TERA MT40 1067 (76.0%)	Isola
✓L5	0.600 mils MIX Base Cu: 0.50 oz VLP-2	Isola
✓L6	5.000 mils Dk: 3.17 I-TERA MT40 (2-1067)	Isola
✓SM	2.400 mils P/G Base Cu: 0.50 oz 1.000 mils VLP-2	
	1.400 mils	



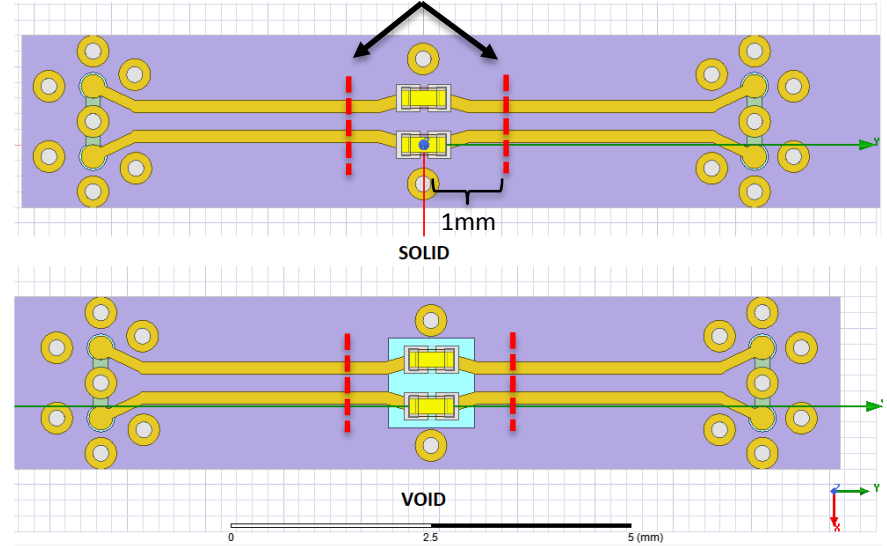
# Design Optimization



# Test Vehicle Preview

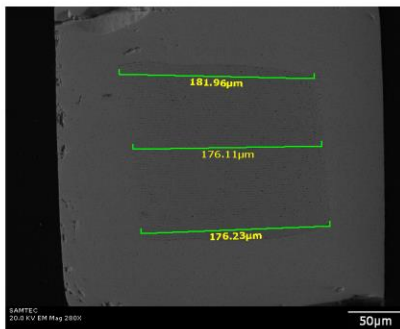


## De-embedded Reference Plane

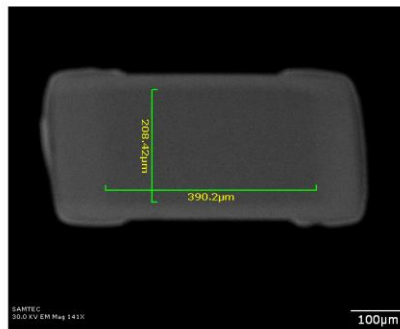




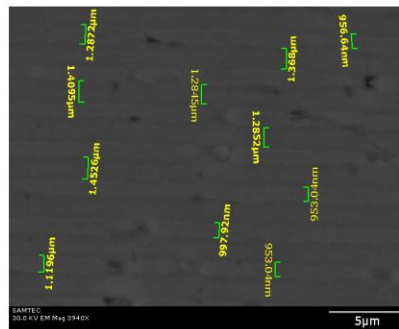
# MLCC SEM Measurements



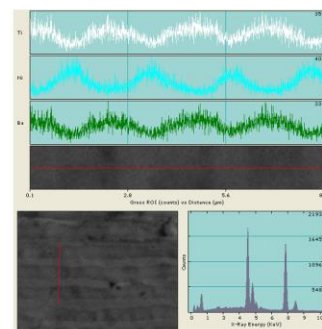
**A. Side View**



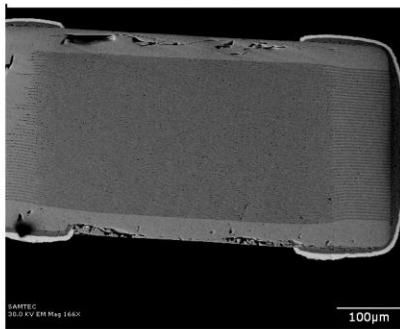
**B. Top View**



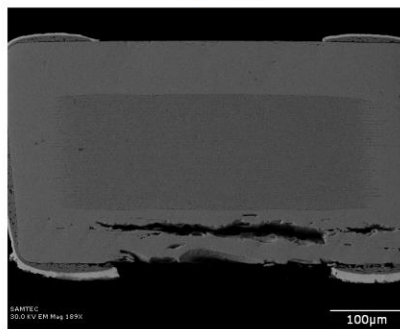
**C. Cross-Section**



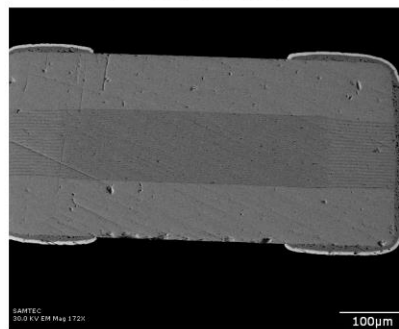
**D. Line Scan**



**E. 220nF Front View**



**F. 150nF Front View**



**G. 47nF Front View**



**H. 22nF Front View**

# HFSS Model

$$C = \frac{E_o * E_r * n * A}{d}$$

C = capacitance

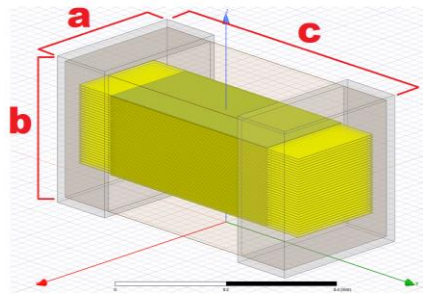
E<sub>o</sub> = vacuum permittivity

E<sub>r</sub> = relative dielectric constant

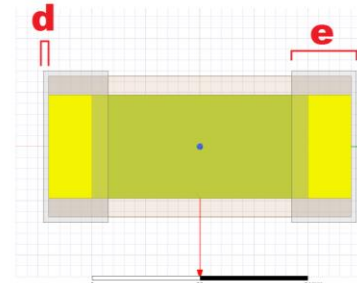
n = number of layers (n + 1 electrodes)

A = area of electrode overlap

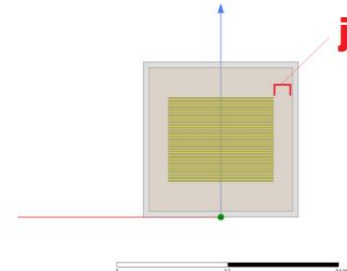
d = dielectric thickness between layers



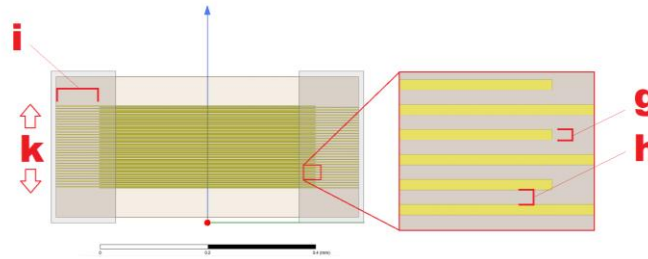
A. Isometric View



B. Top View



C. Side View



D. Front View

Name	Value	Unit	Evaluated Value
\$cap_w	300um-2*\$shell_thk		280um
\$cap_h	300um-2*\$shell_thk		280um
\$cap_l	600um-2*\$shell_thk		580um
\$shell_thk	10	um	10um
\$shell_depth	120	um	120um
\$center_h	\$cap_h/2		140um
\$plate_thk	1	um	1um
\$plate_sep	1.4	um	1.4um
\$plate_clear	80	um	80um
\$shell_gap	35	um	35um
\$nPlate	64		64

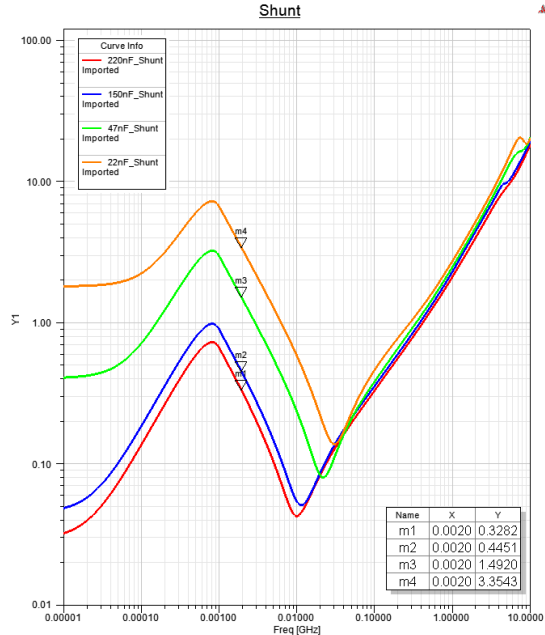
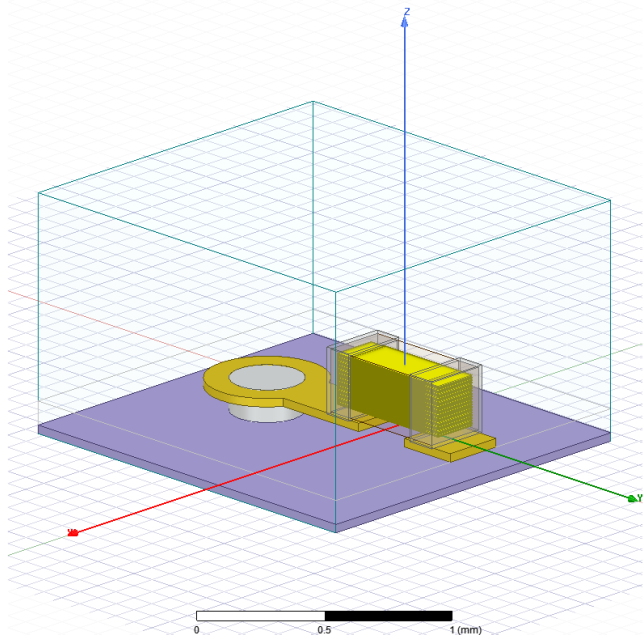
E. Design Variables

Case Size	Capacitor Value (nF)	MFG, P/N	n Plates	Er	Estimated Capacitance (nF)	Tolerance (%)
201	220	TDK, C0603X7S0J224K030BC	90	5000	214.48	-2.51%
201	150	TDK, C0603X7S0J154K030BC	64	5000	151.82	1.21%
201	47	TDK, C0603X7S0J473M030BB	40	2500	46.99	-0.02%
201	22	TDK, C0603X7S0J223K030BB	20	2500	22.89	4.06%



# Shunt Simulation

$$C = \frac{1}{2\pi * f * X_c}$$



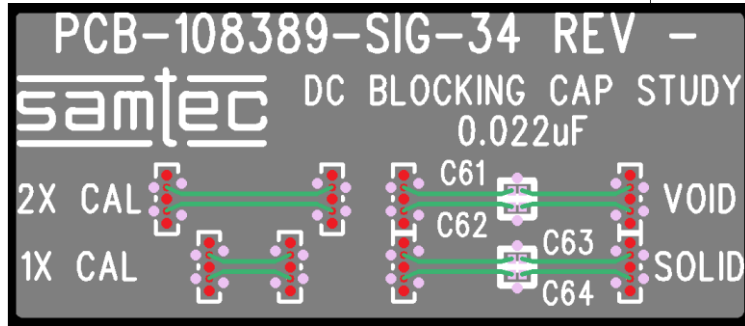
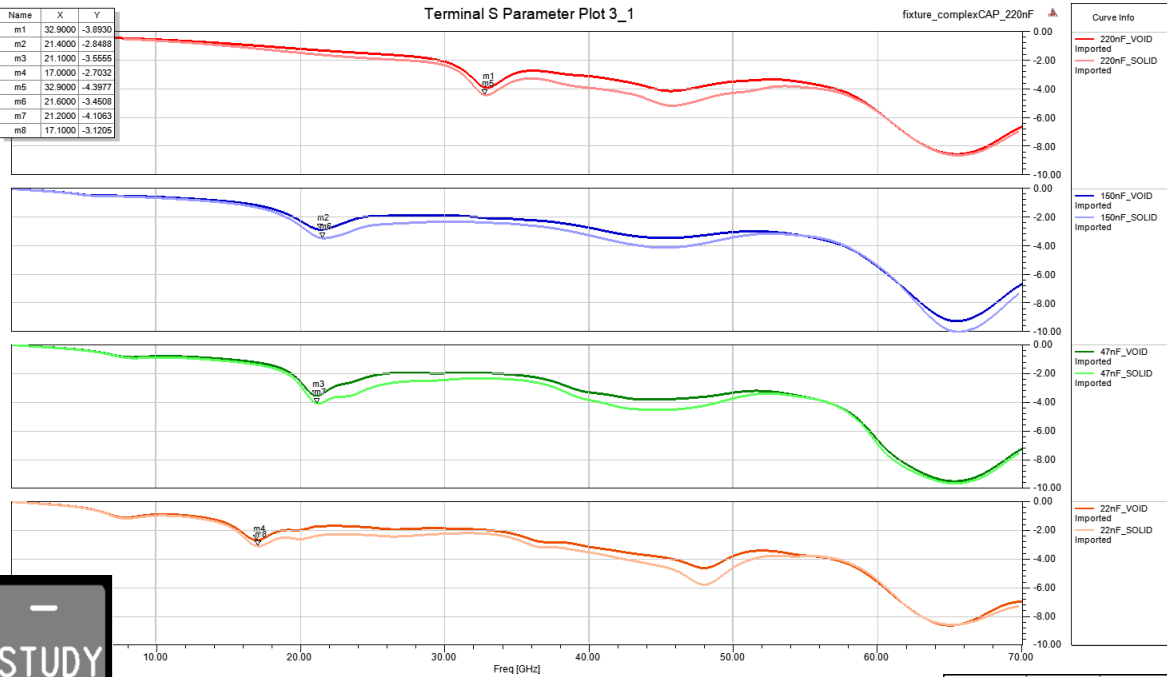
Simulated Reactance X (Ω)	Simulated Capacitance C (nF)	Capacitance Target C (nF)	Difference from Nominal (%)
0.3282	242.47	220	9.3%
0.4451	178.79	150	16.1%
1.4920	53.34	47	11.9%
3.3543	23.72	22	7.3%



# 0201 PKG Family

- Using the test vehicle with 4 different capacitor values and 2 structures (VOID & SOLID) we compare the insertion loss of each
  - 220nF, 150nF, 47nF, 22nF

Name	X	Y
m1	32.9000	-3.8930
m2	21.4000	-2.8488
m3	21.1000	-3.5555
m4	17.0000	-2.7032
m5	32.9000	-4.3977
m6	21.6000	-3.4508
m7	21.2000	-4.1063
m8	17.1000	-3.1205



Name	X	Y
m1	32.9000	-3.8930
m2	21.4000	-2.8488
m3	21.1000	-3.5555
m4	17.0000	-2.7032
m5	32.9000	-4.3977
m6	21.6000	-3.4508
m7	21.2000	-4.1063
m8	17.1000	-3.1205



# Capacitor Modeling

## Sim to Measurement Comparison

### Compare Capacitor Models

1. **SIM 220nF** - All Model Types
2. **SIM 220nF/MEAS All Values** Complex Model (VOID)
3. **SIM 220nF/MEAS All Values** Complex Model (SOLID)

### Channel Exploration

4. **SIM & MEAS 220nF**, Chip to Module Host TX Pkg Only (high loss pkg)
5. **SIM & MEAS 220nF**, Chip to Module Optimistic TX/RX (low loss pkg)

Simulated Measured Both	Capacitor Models			
Value	Complex VOID	Complex SOLID	Shorted VOID	Simple VOID
220nF	X	X	X	X
150nF	X	X		
47nF	X	X		
22nF	X	X		

Diagram annotations: A grey arrow labeled '4 & 5' points to the first column. A blue arrow labeled '1' points to the 'Simple VOID' column. Two red arrows labeled '2' and '3' point to the 'Complex VOID' and 'Complex SOLID' columns respectively.





# What To Pay Attention To

- How do simulation results vary between modeling structures?
- How do capacitor values for a given case size (0201) affect inductance?
- How does the transition geometry (SOLID vs VOID) impact channel performance?
- What impact does loop inductance have on these geometries?



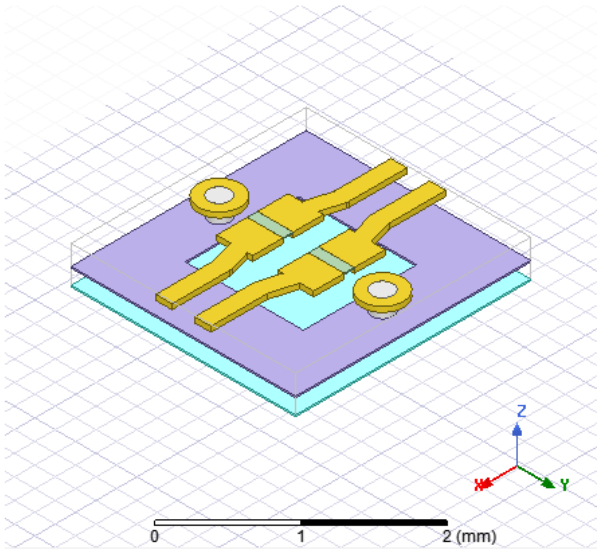
# 1. SIM - 220nF Capacitor, All Model Types



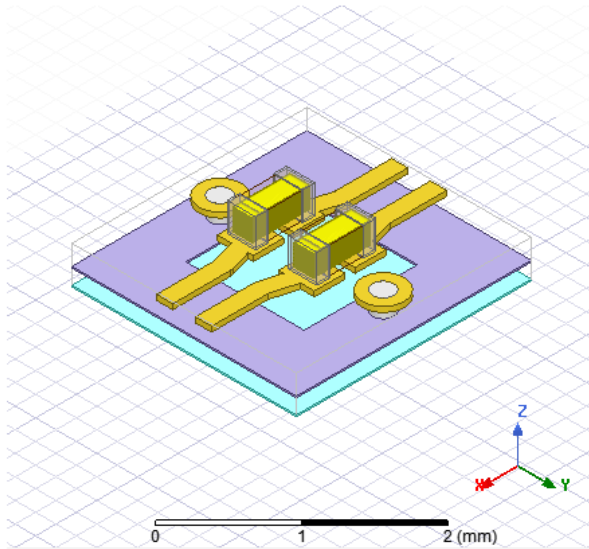
# 1. SIM - 220nF Capacitor, All Model Types

Simulated Measured Both	Capacitor Models			
	Value	Complex VOID	Complex SOLID	Shorted VOID
	220nF	X	X	X
	150nF	X	X	
	47nF	X	X	
	22nF	X	X	

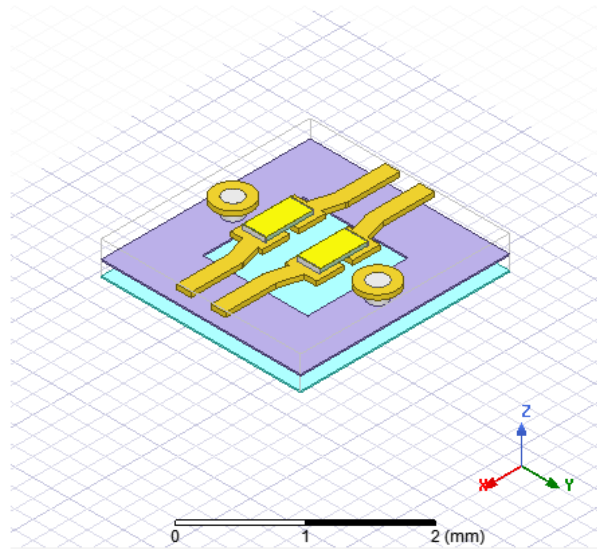
1



SHORT\_VOID



COMPLEX\_VOID



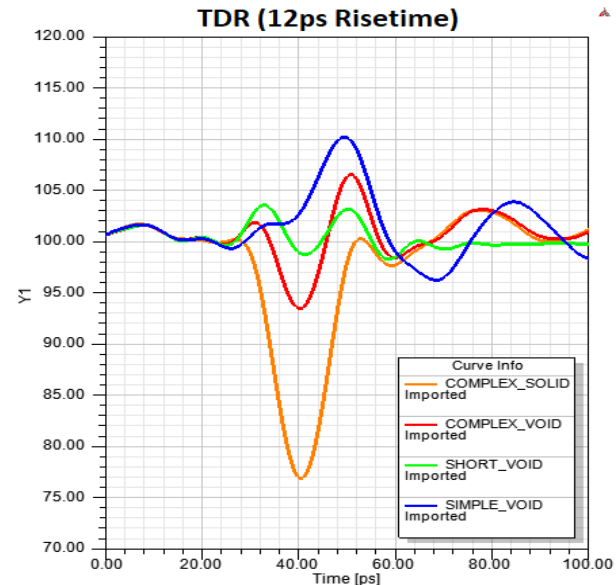
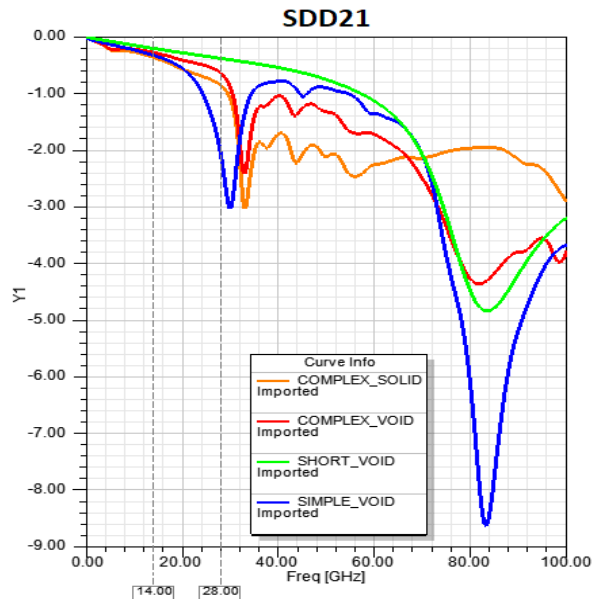
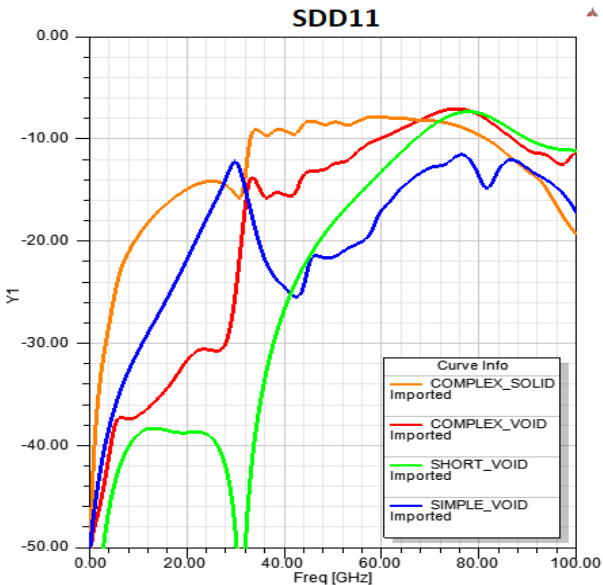
SIMPLE\_VOID



# 1. SIM - 220nF Capacitor, All Model Types

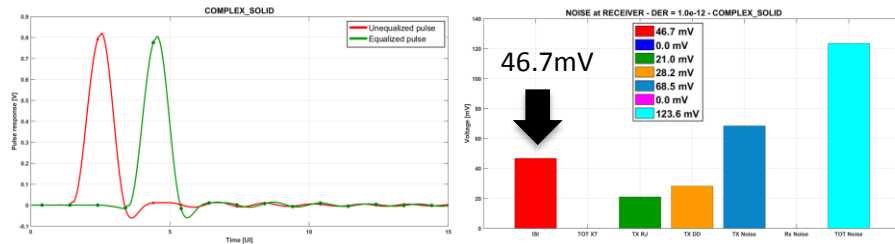
Simulated Measured Both	Capacitor Models			
Value	Complex VOID	Complex SOLID	Shorted VOID	Simple VOID
220nF	X	X	X	X
150nF	X	X		
47nF	X	X		
22nF	X	X		

1

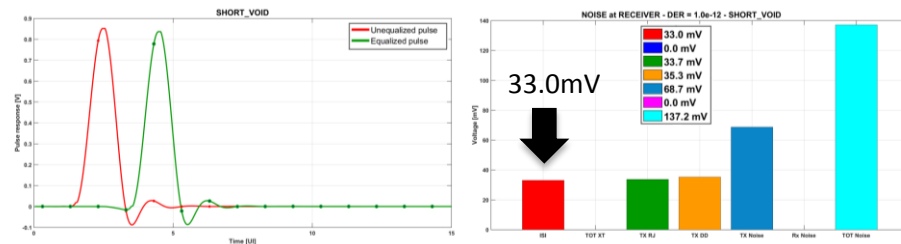


# Model Comparison 56G Single Bit Response

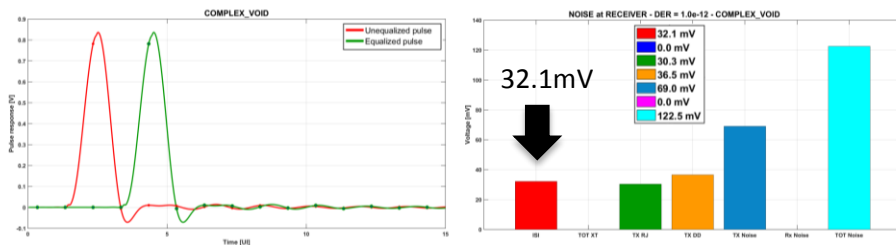
## COMPLEX\_SOLID



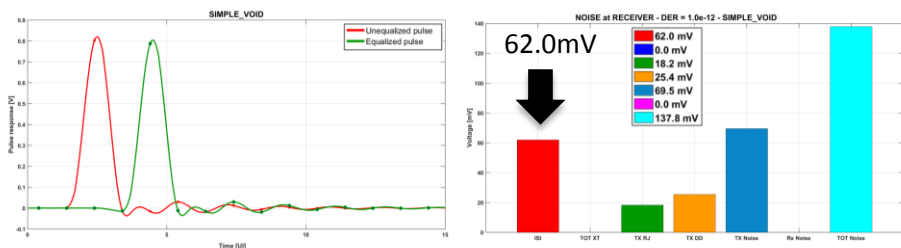
## SHORT\_VOID



## COMPLEX\_VOID



## SIMPLE\_VOID





## 2 & 3. SIM / MEAS - All Measured Values (VOID & SOLID Configuration)

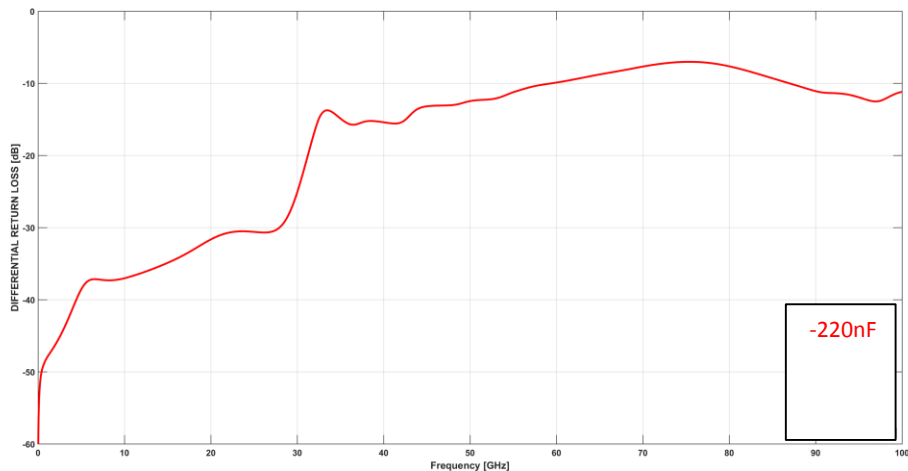


## 2. SIM vs MEAS – SDD11 (VOID)

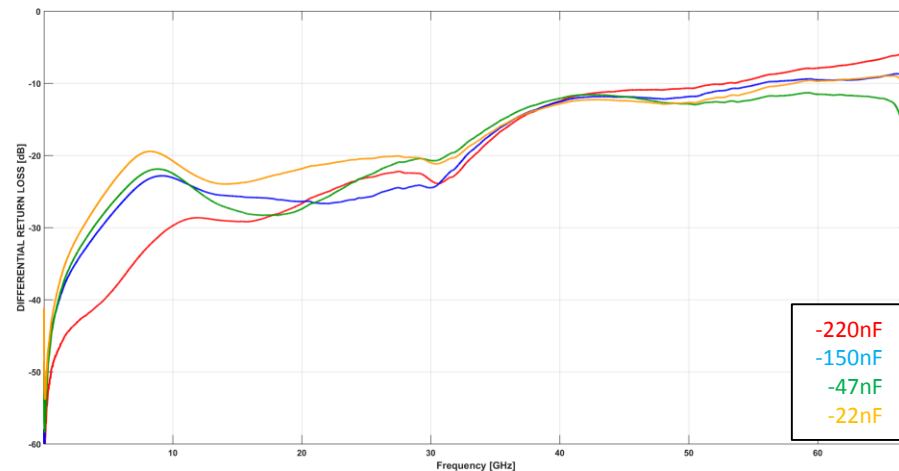
Simulated Measured Both	Capacitor Models			
Value	Complex VOID	Complex SOLID	Shorted VOID	Simple VOID
220nF	X	X	X	X
150nF	X	X		
47nF	X	X		
22nF	X	X		



SIMULATION



MEASUREMENT

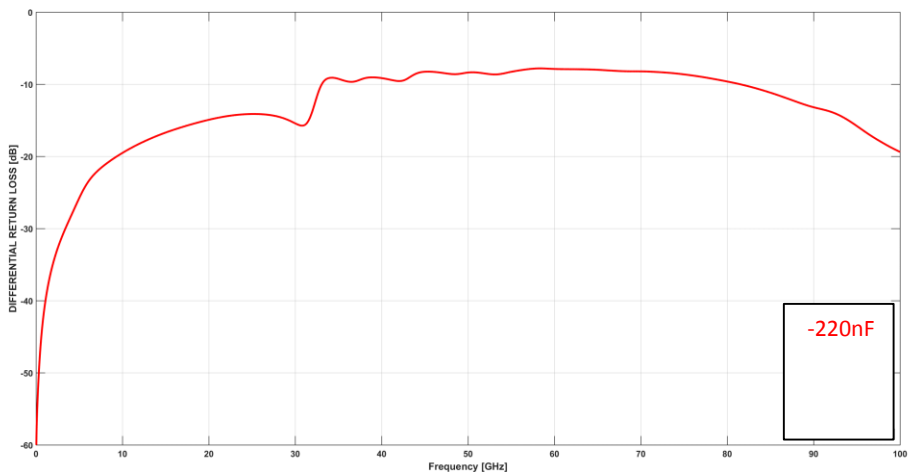


# 3. SIM vs MEAS – SDD11 (SOLID)

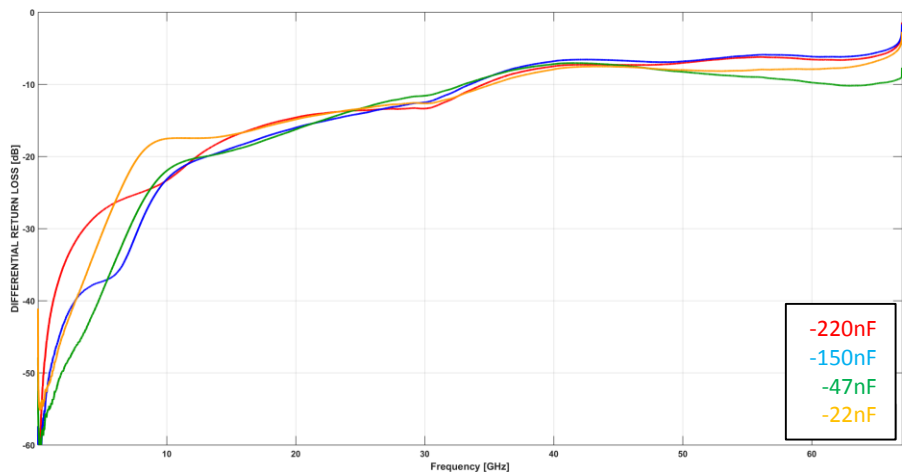
Simulated Measured Both	Capacitor Models			
Value	Complex VOID	Complex SOLID	Shorted VOID	Simple VOID
220nF	X	X	X	X
150nF	X	X		
47nF	X	X		
22nF	X	X		



SIMULATION



MEASUREMENT

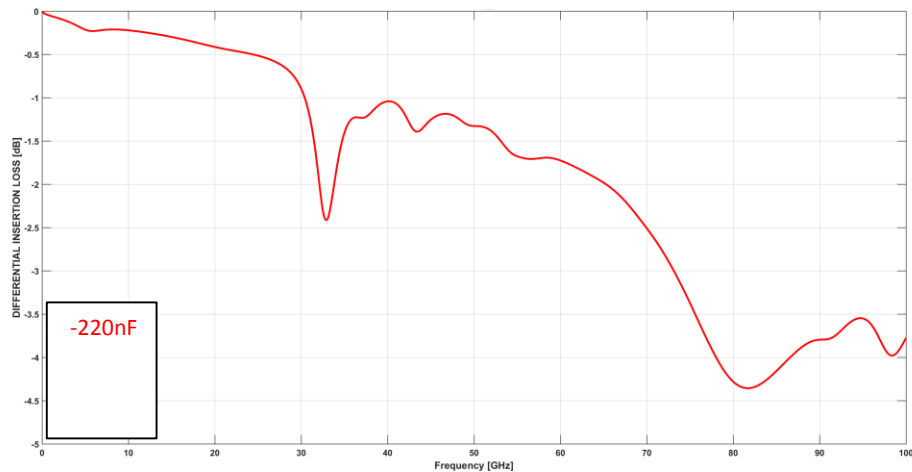


## 2. SIM vs MEAS – SDD21 (VOID)

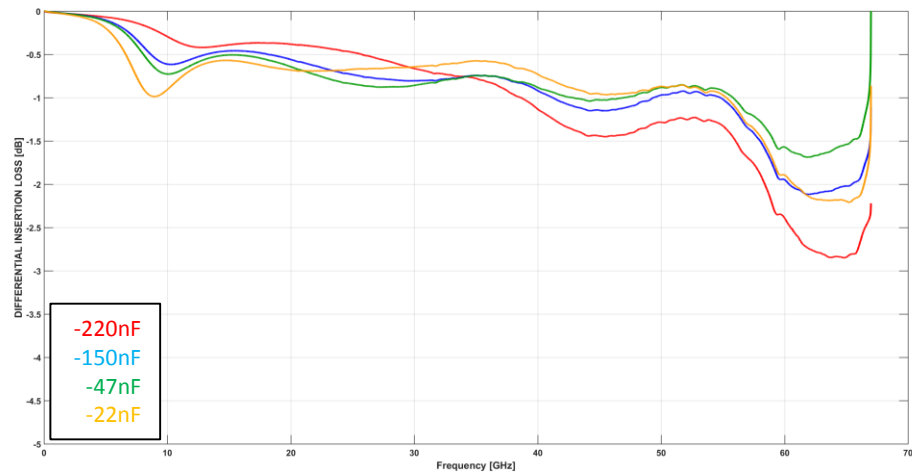
Simulated Measured Both	Capacitor Models			
Value	Complex VOID	Complex SOLID	Shorted VOID	Simple VOID
220nF	X	X	X	X
150nF	X	X		
47nF	X	X		
22nF	X	X		



SIMULATION



MEASUREMENT

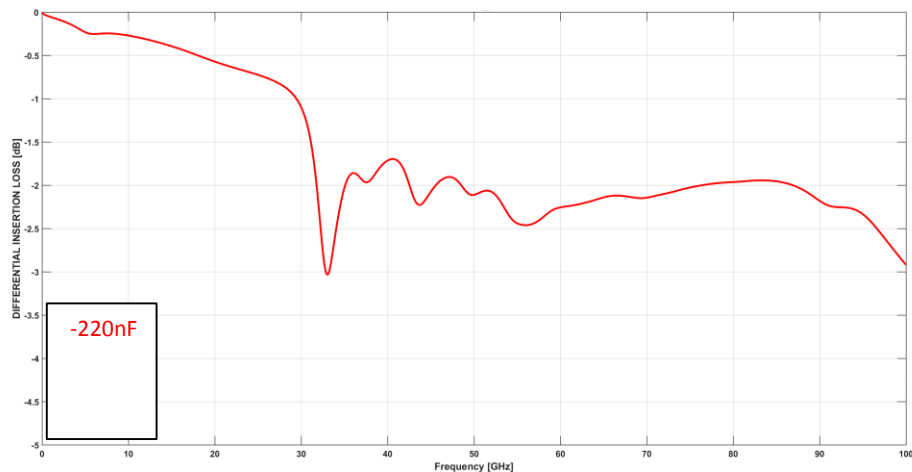


# 3. SIM vs MEAS – SDD21 (SOLID)

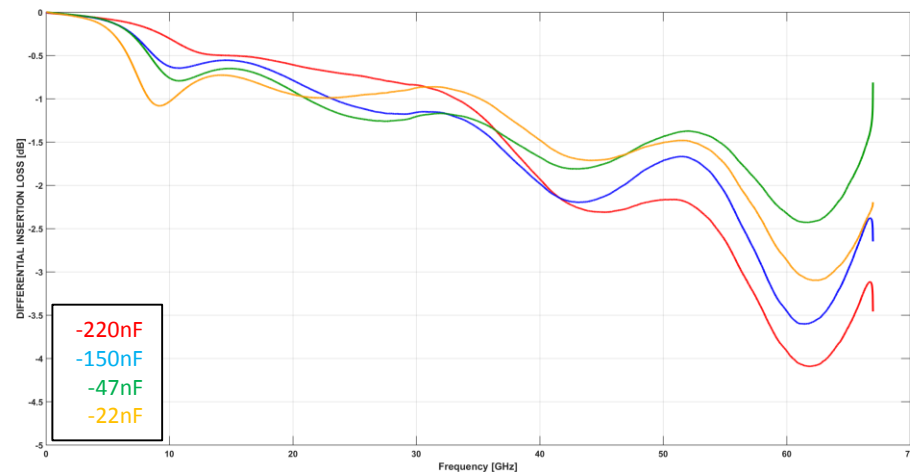
Simulated Measured Both	Capacitor Models			
Value	Complex VOID	Complex SOLID	Shorted VOID	Simple VOID
220nF	X	X	X	X
150nF	X	X		
47nF	X	X		
22nF	X	X		



SIMULATION



MEASUREMENT



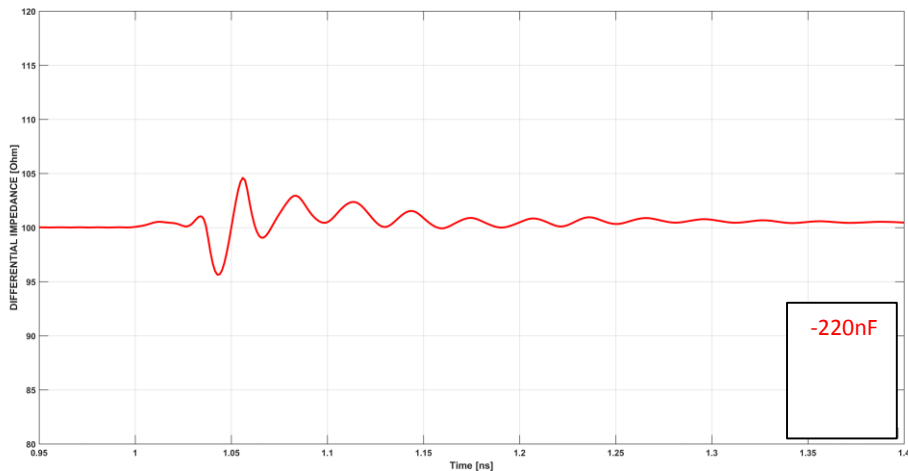


## 2. SIM vs MEAS – TDR, 12ps RT (VOID)

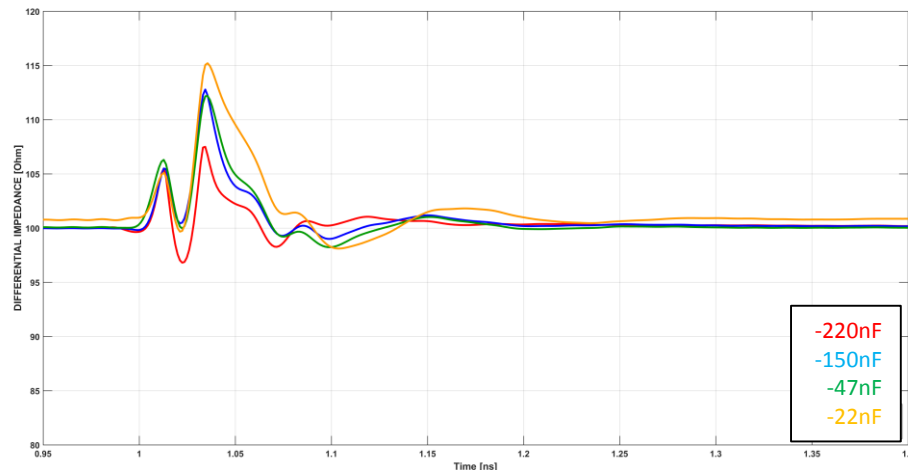
Simulated Measured Both	Capacitor Models			
Value	Complex VOID	Complex SOLID	Shorted VOID	Simple VOID
220nF	X	X	X	X
150nF	X	X		
47nF	X	X		
22nF	X	X		



SIMULATION



MEASUREMENT

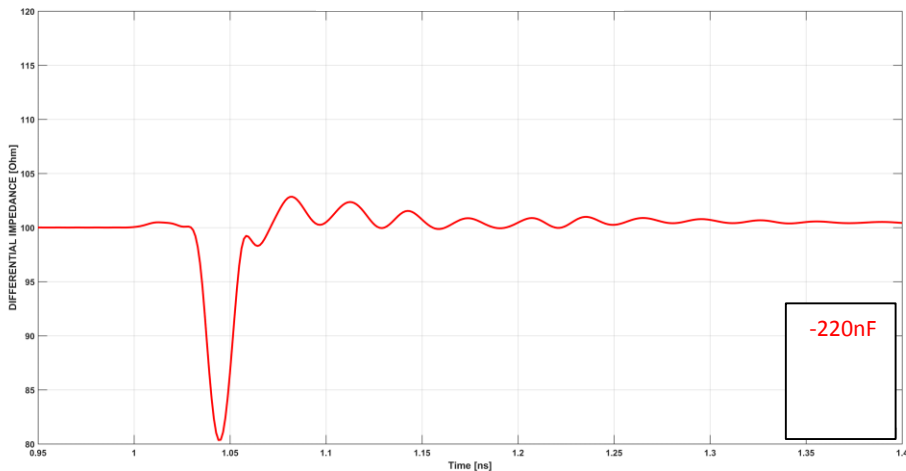


### 3. SIM vs MEAS – TDR, 12ps RT (SOLID)

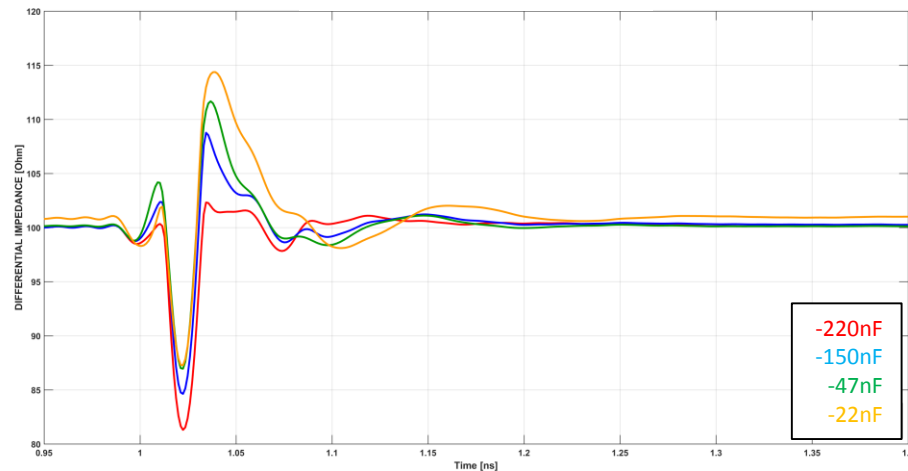
Simulated Measured Both	Capacitor Models			
Value	Complex VOID	Complex SOLID	Shorted VOID	Simple VOID
220nF	X	X	X	X
150nF	X	X		
47nF	X	X		
22nF	X	X		



SIMULATION



MEASUREMENT

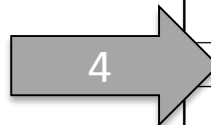


# 4. Chip to Module Exploration

## Simulation to Measurement Comparison

220nF DC Blocking cap with Host Board package only:

- 56G NRZ
- 112G PAM4
- 112G PAM4, 1 TAP DFE
- 112G PAM4, 3 TAP DFE
- 112G PAM4, 12 TAP DFE

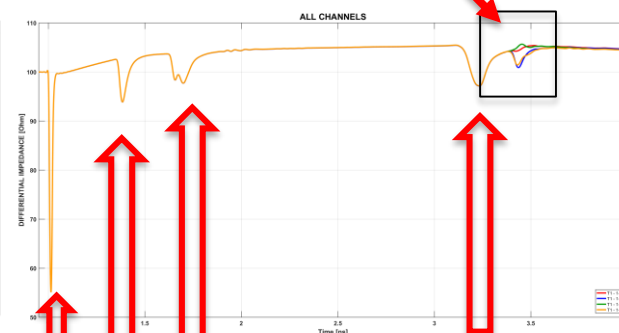
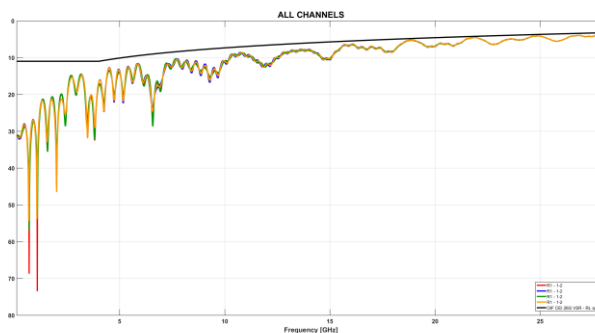
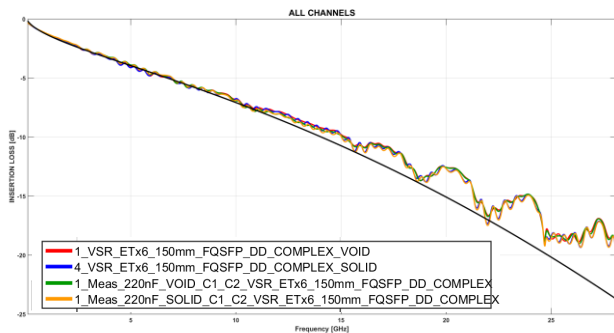
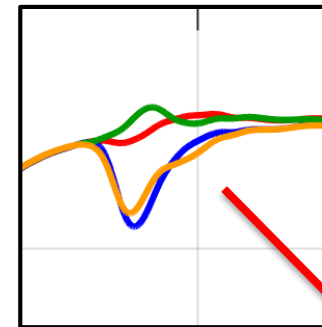
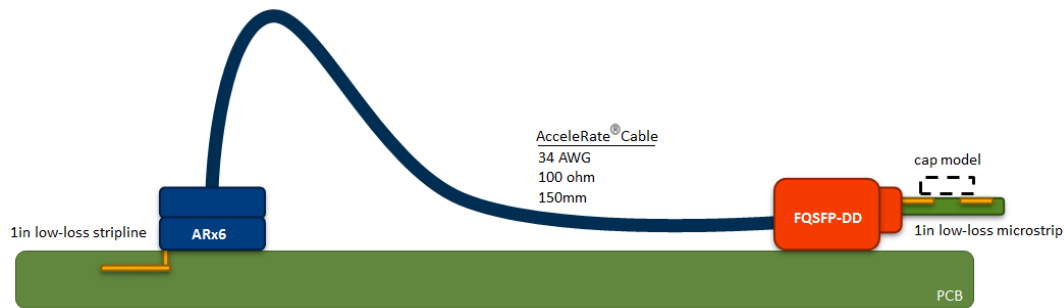


Simulated Measured Both	Capacitor Models			
Value	Complex VOID	Complex SOLID	Shorted VOID	Simple VOID
220nF	X	X	X	X
150nF	X	X		
47nF	X	X		
22nF	X	X		



# 4. Host Package Only Study

## Includes TX Package & 220nF Cap

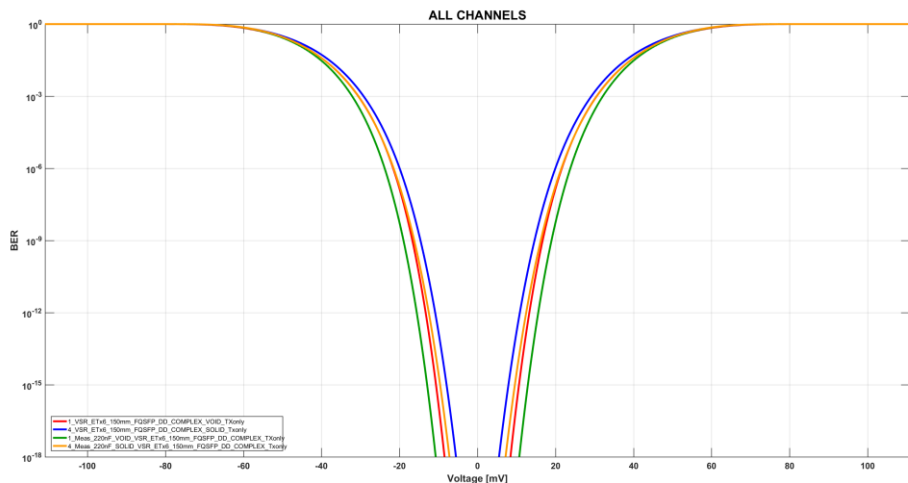


DIE PIN ARx6 FQSFP



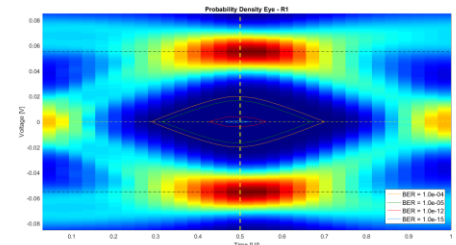
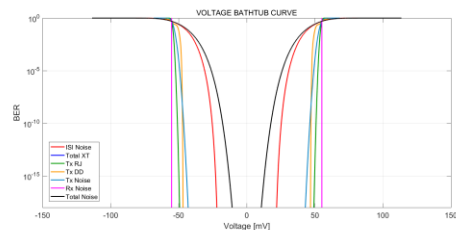
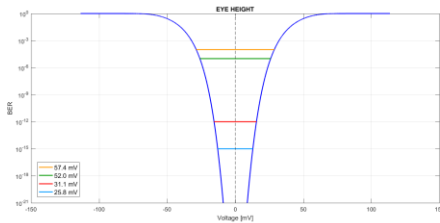
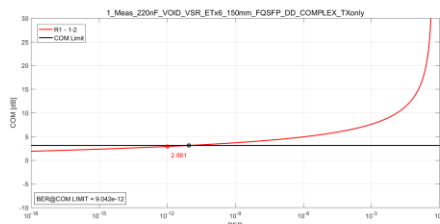
# 56G NRZ

## Voltage Bathtub - All Cases



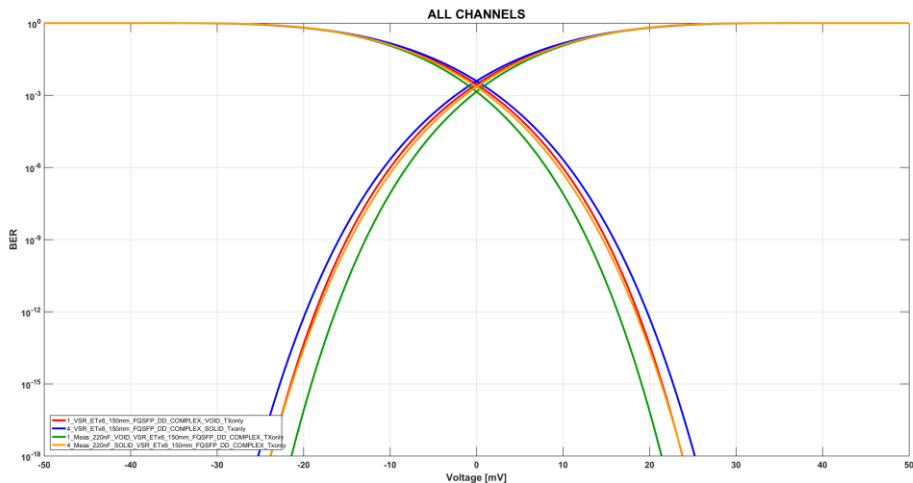
- 1\_VSR\_ETx6\_150mm\_FQSFP\_DD\_COMPLEX\_VOID
- 4\_VSR\_ETx6\_150mm\_FQSFP\_DD\_COMPLEX\_SOLID
- 1\_Meas\_220nF\_VOID\_C1\_C2\_VSR\_ETx6\_150mm\_FQSFP\_DD\_COMPLEX
- 1\_Meas\_220nF\_SOLID\_C1\_C2\_VSR\_ETx6\_150mm\_FQSFP\_DD\_COMPLEX

## Measured VOID



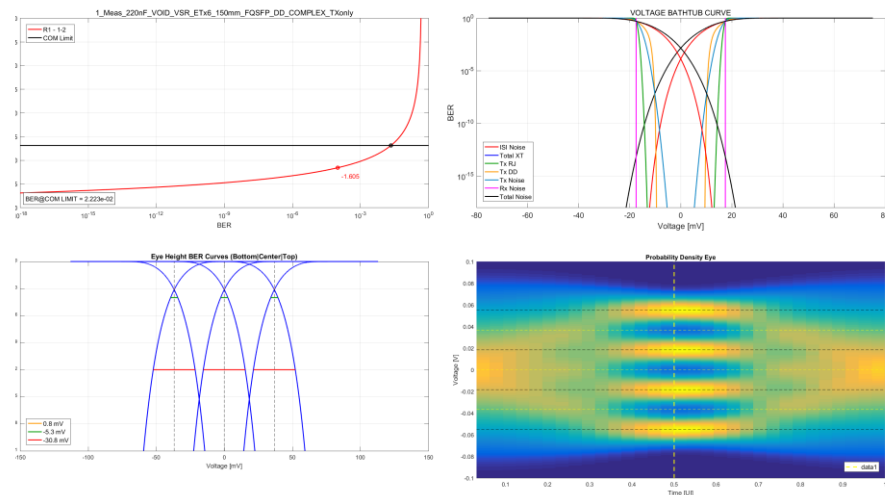
# 112G PAM4

## Voltage Bathtub - All Cases



- 1\_VSR\_ETx6\_150mm\_FQSFP\_DD\_COMPLEX\_VOID
- 4\_VSR\_ETx6\_150mm\_FQSFP\_DD\_COMPLEX\_SOLID
- 1\_Meas\_220nF\_VOID\_C1\_C2\_VSR\_ETx6\_150mm\_FQSFP\_DD\_COMPLEX
- 1\_Meas\_220nF\_SOLID\_C1\_C2\_VSR\_ETx6\_150mm\_FQSFP\_DD\_COMPLEX

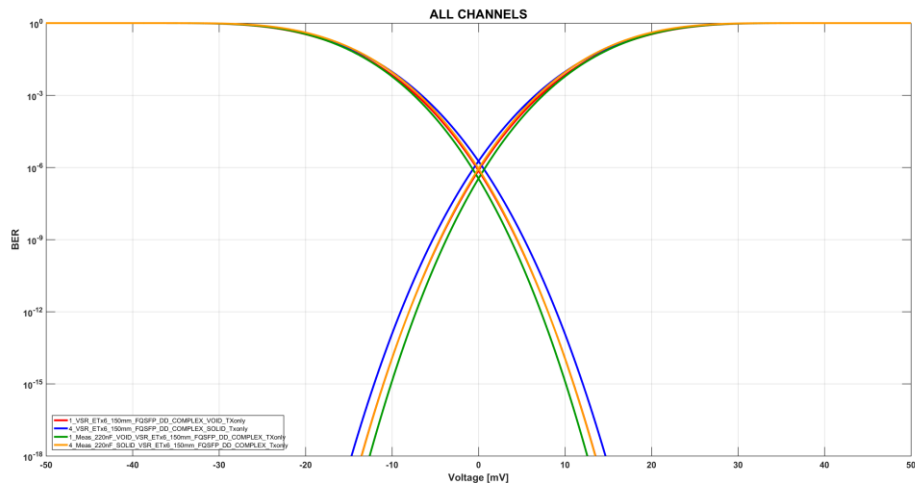
## Measured VOID





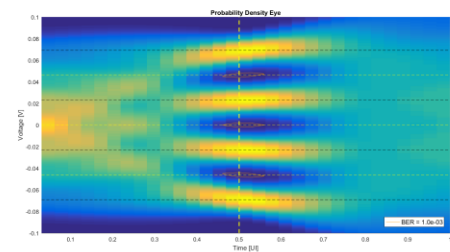
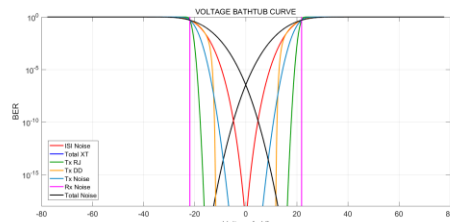
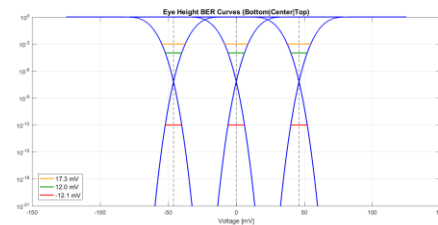
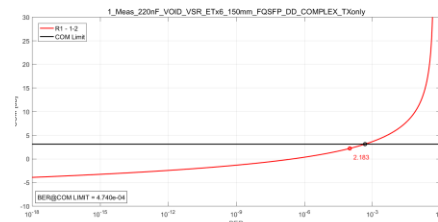
# 112G PAM4 3 TAP DFE

## Voltage Bathtub - All Cases



- 1\_VSR\_ETx6\_150mm\_FQSFP\_DD\_COMPLEX\_VOID
- 4\_VSR\_ETx6\_150mm\_FQSFP\_DD\_COMPLEX\_SOLID
- 1\_Meas\_220nF\_VOID\_C1\_C2\_VSR\_ETx6\_150mm\_FQSFP\_DD\_COMPLEX
- 1\_Meas\_220nF\_SOLID\_C1\_C2\_VSR\_ETx6\_150mm\_FQSFP\_DD\_COMPLEX

## Measured VOID

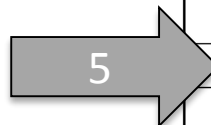


# 5. Chip to Module Exploration

## Simulation to Measurement Comparison

220nF DC Blocking cap with optimistic TX/RX package:

- 56G NRZ
- 112G PAM4
- 112G PAM4, 1 TAP DFE
- 112G PAM4, 3 TAP DFE
- 112G PAM4, 12 TAP DFE

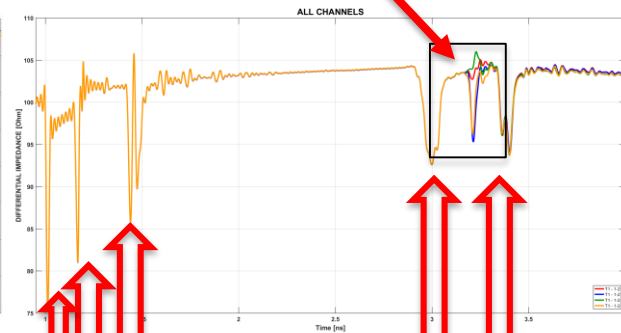
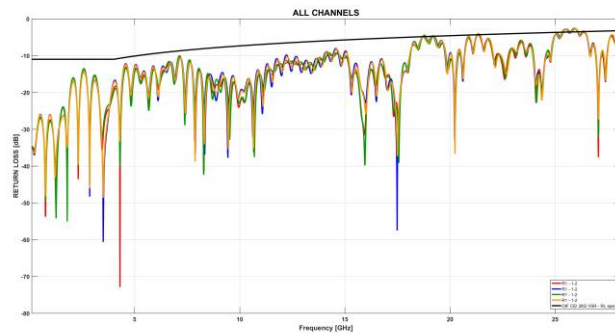
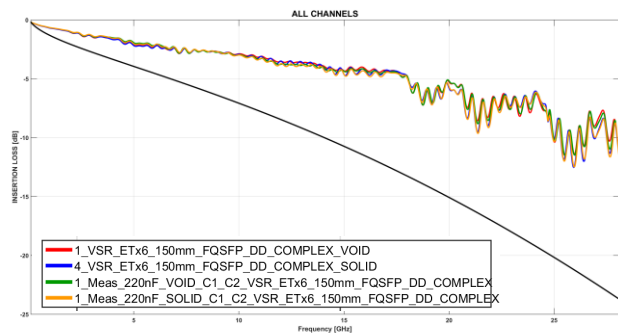
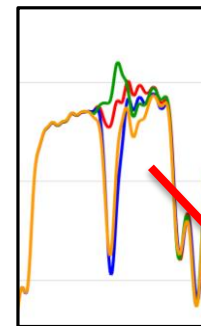
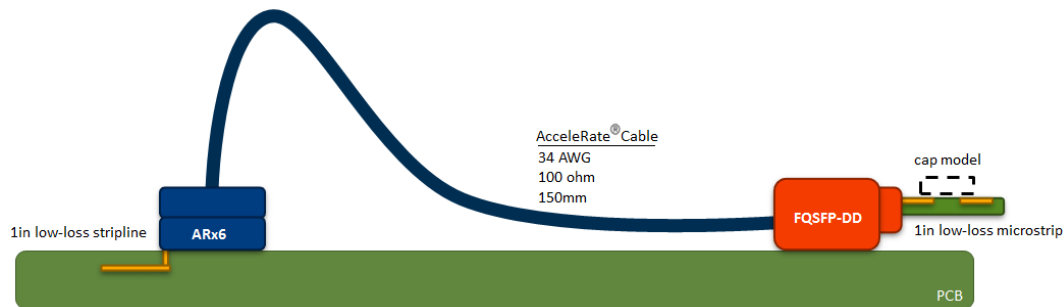


Simulated Measured Both	Capacitor Models			
	Complex VOID	Complex SOLID	Shorted VOID	Simple VOID
Value				
220nF	X	X	X	X
150nF	X	X		
47nF	X	X		
22nF	X	X		



# 5. Optimistic Host/Module Package Study

## Includes TX/RX Package & 220nF Cap



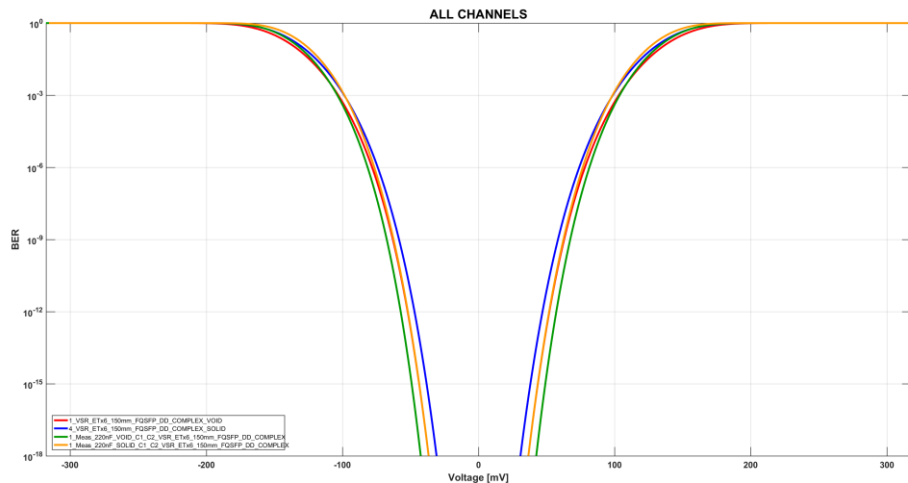
DIE PIN ARx6

FQSFP PKG



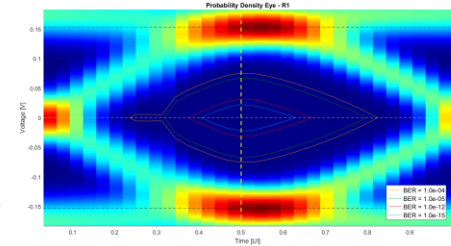
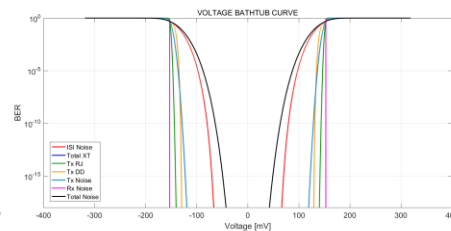
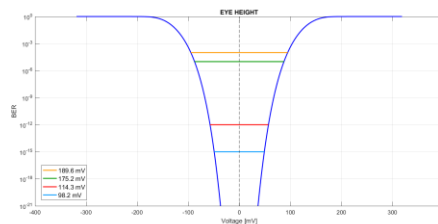
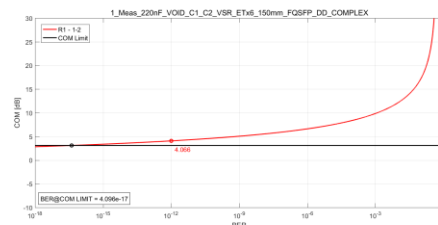
# 56G NRZ

## Voltage Bathtub - All Cases



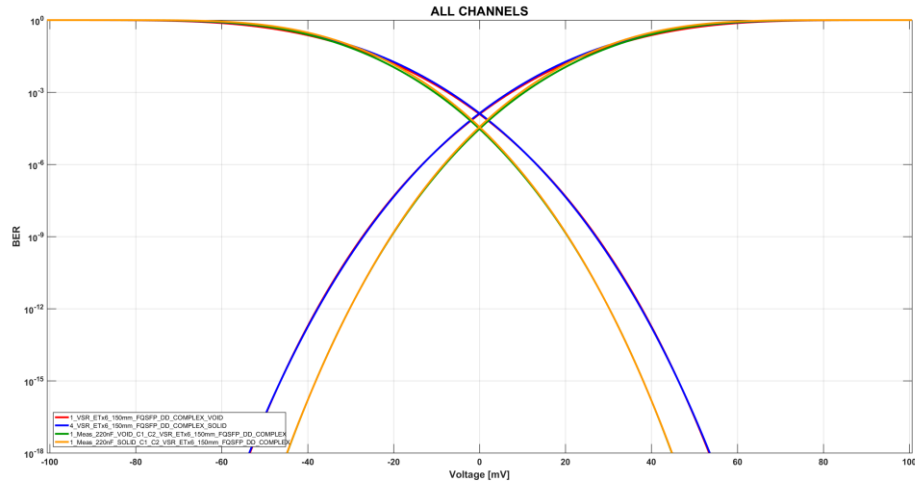
- 1\_VSR\_ETx6\_150mm\_FQSFP\_DD\_COMPLEX\_VOID
- 4\_VSR\_ETx6\_150mm\_FQSFP\_DD\_COMPLEX\_SOLID
- 1\_Meas\_220nF\_VOID\_C1\_C2\_VSR\_ETx6\_150mm\_FQSFP\_DD\_COMPLEX
- 1\_Meas\_220nF\_SOLID\_C1\_C2\_VSR\_ETx6\_150mm\_FQSFP\_DD\_COMPLEX

## Measured VOID



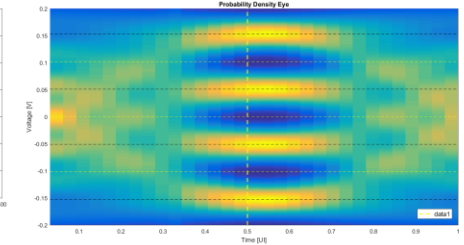
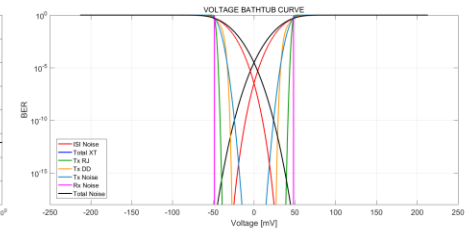
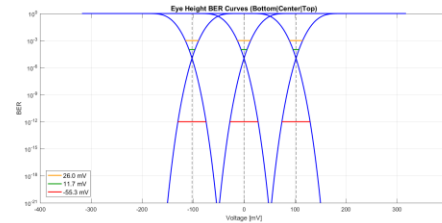
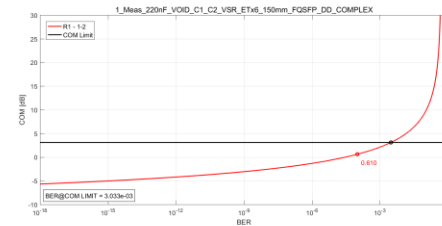
# 112G PAM4

## Voltage Bathtub - All Cases



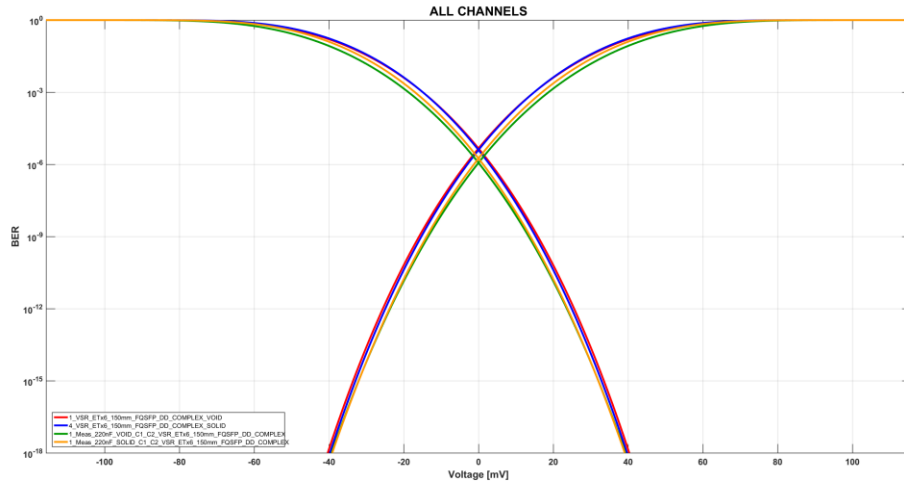
- 1\_VSR\_ETx6\_150mm\_FQSFP\_DD\_COMPLEX\_VOID
- 4\_VSR\_ETx6\_150mm\_FQSFP\_DD\_COMPLEX\_SOLID
- 1\_Meas\_220nF\_VOID\_C1\_C2\_VSR\_ETx6\_150mm\_FQSFP\_DD\_COMPLEX
- 1\_Meas\_220nF\_SOLID\_C1\_C2\_VSR\_ETx6\_150mm\_FQSFP\_DD\_COMPLEX

## Measured VOID



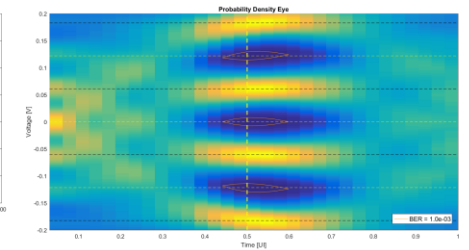
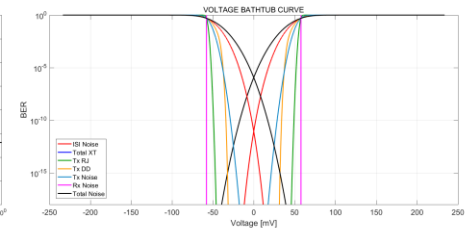
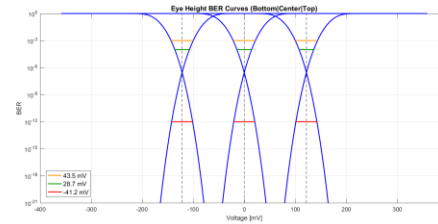
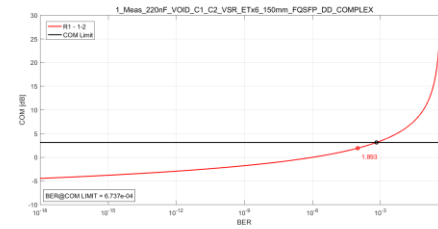
# 112G PAM4 3 TAP DFE

## Voltage Bathtub - All Cases



- 1\_VSR\_ETx6\_150mm\_FQSFP\_DD\_COMPLEX\_VOID
- 4\_VSR\_ETx6\_150mm\_FQSFP\_DD\_COMPLEX\_SOLID
- 1\_Meas\_220nF\_VOID\_C1\_C2\_VSR\_ETx6\_150mm\_FQSFP\_DD\_COMPLEX
- 1\_Meas\_220nF\_SOLID\_C1\_C2\_VSR\_ETx6\_150mm\_FQSFP\_DD\_COMPLEX

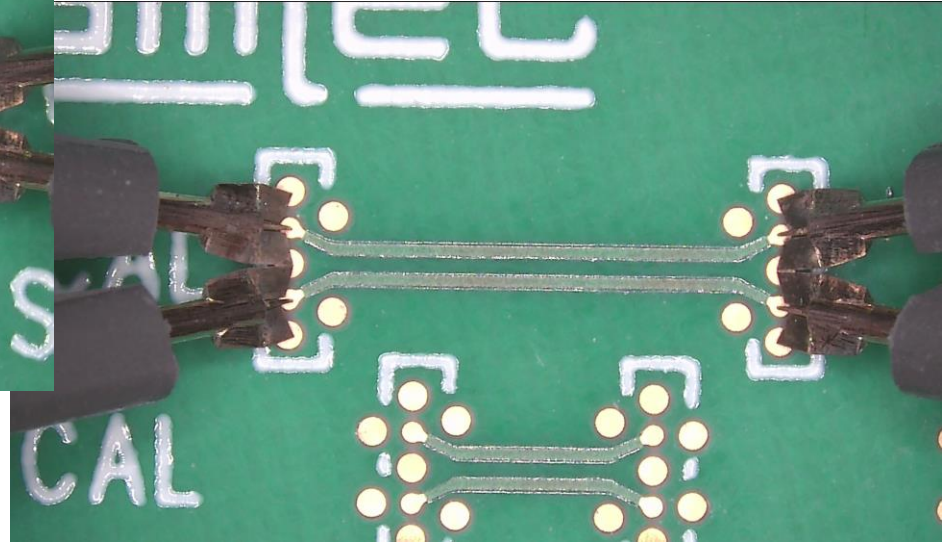
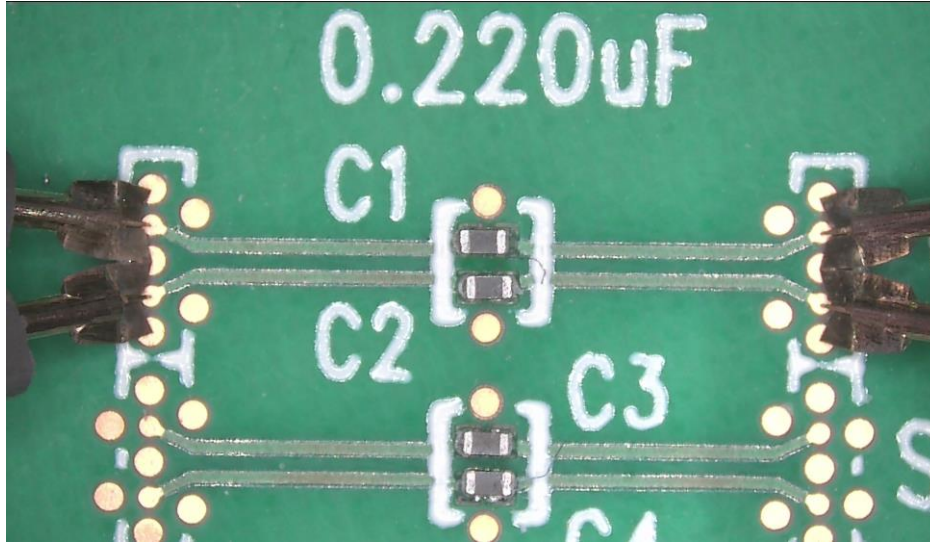
## Measured VOID





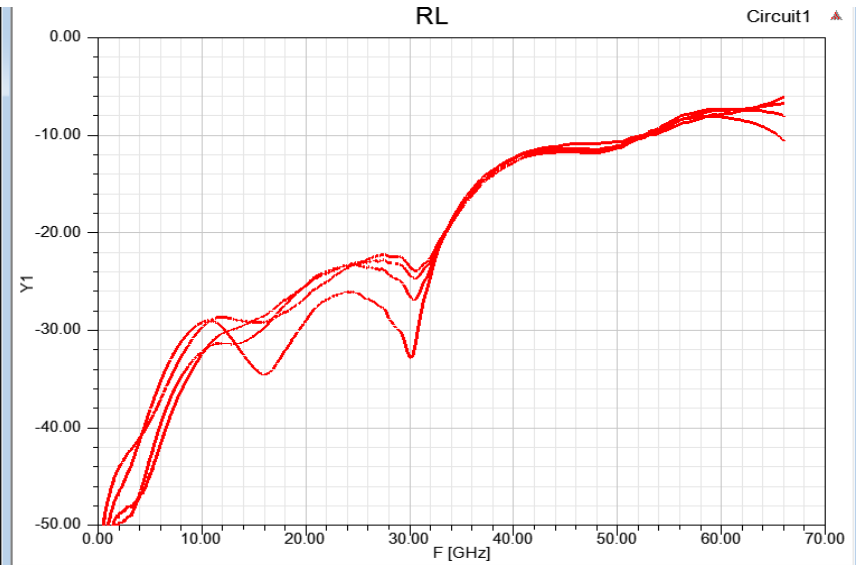
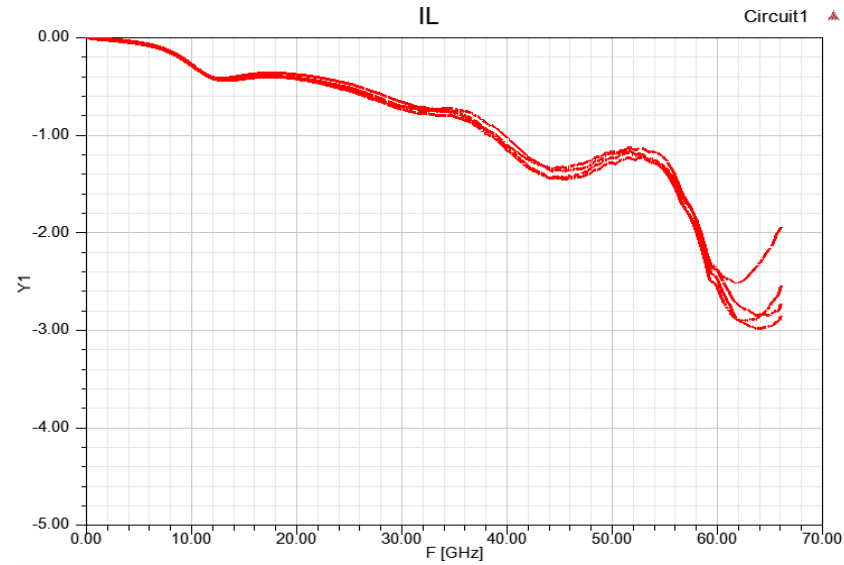
# Test Vehicle Correlation Work

## VOID, SOLID, & CAL Layouts



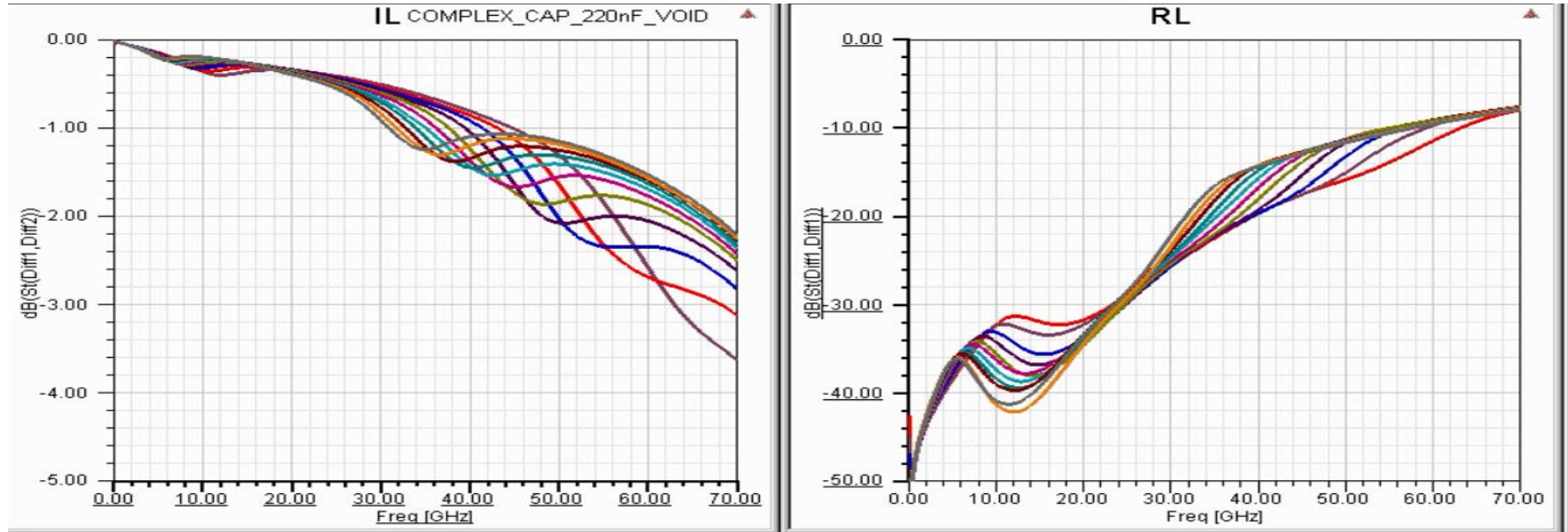
# Test Vehicle Correlation Work

## 220nF VOID Measurements



# Test Vehicle Correlation Work

## 220nF VOID Simulation v2.0



# Thank you!



## QUESTIONS?

